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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SATOSHI ASANO	11/30/2012
MASAHIRO MATSUMOTO	11/30/2012
HIROSHI NAKANO	11/30/2012

RECEIVING PARTY DATA

Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.	
Street Address:	2520, TAKABA	
City:	HITACHINAKA-SHI, IBARAKI	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13814855

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 091442-0157

NAME OF SUBMITTER: P. SHIEK FOR W. T. ELLIS

Total Attachments: 1 source=assign#page1.tif

PATENT REEL: 029775 FRAME: 0199 OF \$40.00 1381485

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd.,

a corporation organized under the laws of Japan,

located at 2520, Takaba, Hitachinaka-shi, Ibaraki Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said. Hitachi Automotive Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

THERMAL FLOWMETER

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi Automotive Systems, Ltd.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Automotive Systems, Ltd.,

Signed on the date(s) indicated aside our signatures:

RECORDED: 02/07/2013

INVENTUR(S)		Date Signed (署名日)
(発明者フルネームサイン)		(有行口)
1)_	Satoshi Asano satoshi ASANO	11/30/2012
	Masahiro Matsumo Masahiro MATSUMOTO	11/20/20/2
3)_	Hiroshi Nakano Hiroshi NAKANO	11/30/2012
4)_		
5)_		
6)_		
7)_		
8)		
9)		
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10)_		

PATENT REEL: 029775 FRAME: 0200